

RSD221N06

Nch 60V 22A Power MOSFET

V_{DSS}	60V
R _{DS(on)} (Max.)	26m Ω
I _D	22A
P_D	20W

● Features

- 1) Low on-resistance.
- 2) Fast switching speed.
- 3) Drive circuits can be simple.
- 4) Parallel use is easy.
- 5) Pb-free lead plating; RoHS compliant
- 6) 100% Avalanche tested

Application

Switching Power Supply

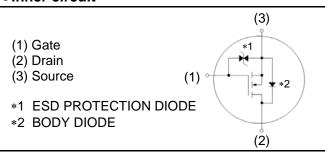
Automotive Motor Drive

Automotive Solenoid Drive

Outline

CPT3 (SC-63) <SOT-428>

●Inner circuit



Packaging specifications

	Packaging	Taping
	Reel size (mm)	330
Typo	Tape width (mm)	16
Туре	Basic ordering unit (pcs)	2,500
	Taping code	TL
	Marking	221N06

• Absolute maximum ratings $(T_a = 25^{\circ}C)$

Parameter	Symbol	Value	Unit	
Drain - Source voltage		V_{DSS}	60	V
Continuous drain current	T _c = 25°C	I _D *1	±22	А
	T _c = 100°C	I _D *1	±11	А
Pulsed drain current		I _{D,pulse} *2	±44	А
Gate - Source voltage		V_{GSS}	±20	V
Avalanche energy, single pulse		E _{AS} *3	17.8	mJ
Avalanche current		I _{AR} *3	22	А
$T_c = 25$ °C		P _D	20	W
Power dissipation $T_a = 25^{\circ}C$		P _D	0.85	W
Junction temperature		T _j	150	°C
Range of storage temperature		T _{stg}	-55 to +150	°C

●Thermal resistance

Parameter	Symbol	Values			Unit
raiametei	Symbol	Min.	Тур.	Max.	Offic
Thermal resistance, junction - ambient	R _{thJC}	-	-	6.25	°C/W

•Electrical characteristics($T_a = 25$ °C)

Doromotor	Symbol	Conditions	Values			Unit	
Parameter	Parameter Symbol Con		Min.	Тур.	Max.		
Drain - Source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V$, $I_D = 1mA$	60	ı	ı	V	
		$V_{DS} = 60V, V_{GS} = 0V$			1		
Zara gata valtaga drain avrent		T _j = 25°C	-	-	1	μА	
Zero gate voltage drain current	I _{DSS}	$V_{DS} = 60V, V_{GS} = 0V$			100		
		T _j = 125°C	-	-	100		
Gate - Source leakage current	I _{GSS}	$V_{GS} = \pm 20V, V_{DS} = 0V$	-	-	±10	μΑ	
Gate threshold voltage	V _{GS (th)}	$V_{DS} = 10V$, $I_D = 1mA$	1.0	-	3.0	V	
		$V_{GS} = 10V, I_D = 22A$	-	18	26		
		$V_{GS} = 4.5V, I_D = 22A$	-	21	30		
Static drain - source on - state resistance	$R_{DS(on)}^{}^{\star 4}}$	$V_{GS} = 4.0V, I_D = 22A$	-	23	33	mΩ	
		$V_{GS} = 10V, I_D = 22A$		20	45	1	
		T _j = 125°C	-	32	45		
Forward transfer admittance	9 _{fs}	$V_{DS} = 10V, I_D = 22A$	12	24	-	S	

●Electrical characteristics(T_a = 25°C)

Parameter	Symbol	Conditions	Values			Unit
r ai ai ii e lei	Syllibol	Conditions	Min.	Тур.	Max.	Offic
Input capacitance	C_{iss}	$V_{GS} = 0V$	-	1500	1	
Output capacitance	C _{oss}	V _{DS} = 10V	-	320	1	pF
Reverse transfer capacitance	C_{rss}	f = 1MHz	-	140	1	
Turn - on delay time	t _{d(on)} *4	$V_{DD} \simeq 30V, V_{GS} = 10V$	-	25	1	
Rise time	t _r *4	I _D = 11A	-	45	1	no
Turn - off delay time	t _{d(off)} *4	$R_L = 12\Omega$	-	75	-	ns
Fall time	t _f *4	$R_G = 10\Omega$	-	65	-	

● Gate Charge characteristics (T_a = 25°C)

Parameter	Symbol	Conditions	Values			Unit
Parameter	Symbol Conditions -		Min.	Тур.	Max.	Offic
Total gate charge	Q_g^{*4}	$V_{DD} \simeq 30V$	-	30	-	
Gate - Source charge	Q _{gs} *4	I _D = 22A	-	4.5	-	nC
Gate - Drain charge	Q _{gd} *4	V _{GS} = 10V	-	3.0	-	
Gate plateau voltage	V _(plateau)	$V_{DD} \simeq 30V$, $I_D = 22A$	-	3.3	-	V

●Body diode electrical characteristics (Source-Drain)(T_a = 25°C)

Parameter	Symbol	Conditions	Values			Unit
r ai ai i letei	Symbol	ymbol Conditions -		Тур.	Max.	Offic
Continuous source current	l _S *1	T _c = 25°C	ı	-	16	Α
Pulsed source current	I _{SM} *2	1 c = 20 O	-	-	44	Α
Forward voltage	V_{SD}^{*4}	$V_{GS} = 0V, I_{S} = 22A$	-	-	1.2	V
Reverse recovery time	t _{rr} *4	I _S = 22A	ı	56	ı	ns
Reverse recovery charge	Q _{rr} *4	di/dt = 100A/μs	-	100	-	μС

^{*1} Limited only by maximum temperature allowed.

^{*2} Pw \leq 10 μ s, Duty cycle \leq 1%

^{*3} L \simeq 50 μ H, V_{DD} = 30V, Rg = 10 Ω , starting T_j = 25°C

^{*4} Pulsed

Fig.1 Power Dissipation Derating Curve

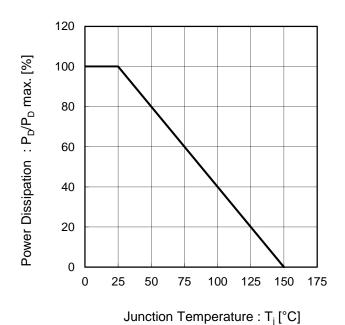
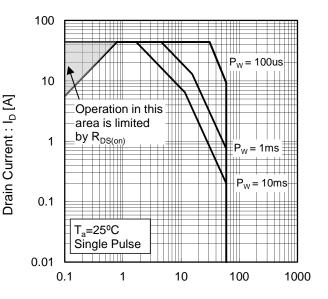
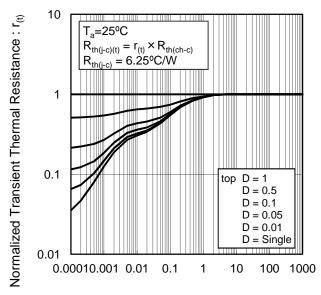


Fig.2 Maximum Safe Operating Area



Drain - Source Voltage : V_{DS} [V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width



Pulse Width: P_W[s]

Fig.4 Avalanche Current vs Inductive Load

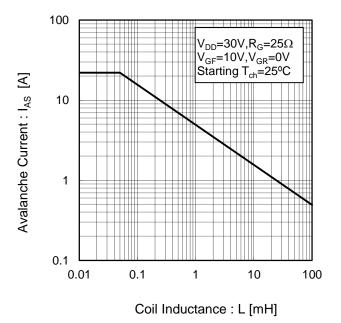
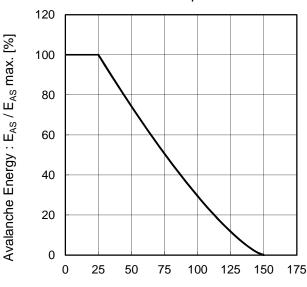
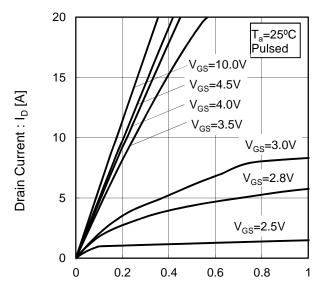


Fig.5 Avalanche Energy Derating Curve vs Junction Temperature



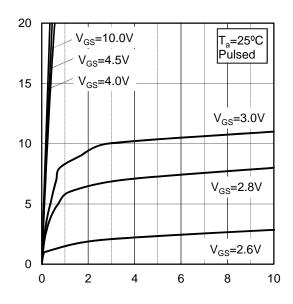
Junction Temperature : T_i [°C]

Fig.6 Typical Output Characteristics(I)



Drain - Source Voltage : V_{DS} [V]

Fig.7 Typical Output Characteristics(II)



Drain - Source Voltage : V_{DS} [V]

Drain Current : I_D [A]

Fig.8 Breakdown Voltage vs. Junction Temperature 80 Normarize Drain - Source Breakdown Voltage : $V_{(BR)DSS}$ [V] $V_{GS} = 0V$ 75 $I_D = 1 \text{mA}$ 70 65 60 55 50 45 40 -50 50 100 150 Junction Temperature : T_i [°C]

100 V_{DS}= 10V 10 V_{DS}= 10V T_a= 125°C T_a= 75°C T_a= 75°C T_a= 25°C T_a= -25°C

Fig.9 Typical Transfer Characteristics

Fig.10 Gate Threshold Voltage vs. Junction Temperature

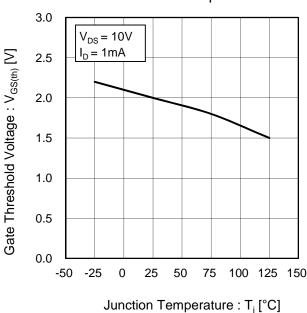
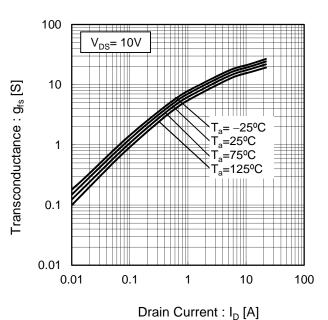


Fig.11 Transconductance vs. Drain Current

Gate - Source Voltage : V_{GS} [V]



Resistance vs. Gate Source Voltage 100 Static Drain - Source On-State Resistance T_a=25°C Static Drain - Source On-State Resistance 80 = 11A60 $:R_{DS(on)}\left[m\Omega \right]$ $: R_{\text{DS(on)}} \left[\text{m}\Omega\right]$ $I_{D} = 22A$ 40 20 0 0 5 10 15

Fig.12 Static Drain - Source On - State

Fig.13 Static Drain - Source On - State
Resistance vs. Drain Current(I)

100

V_{GS}= 10V
V_{GS}= 4.5V
V_{GS}= 4.0V

10

0.01

0.1

Drain Current : I_D [A]

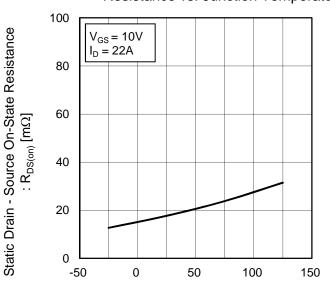
10

100

1

Fig.14 Static Drain - Source On - State Resistance vs. Junction Temperature

Gate - Source Voltage : V_{GS} [V]



Junction Temperature : T_j [°C]

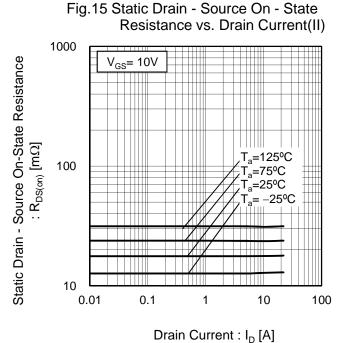


Fig.16 Static Drain - Source On - State Resistance vs. Drain Current(III)

1000 $V_{GS} = 4.5V$ $T_a = 125^{\circ}C$ $T_a = 75^{\circ}C$ $T_a = -25^{\circ}C$ $T_a = -25^{\circ}C$

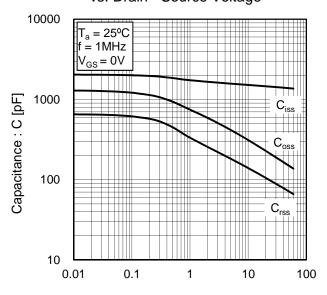
Fig.17 Static Drain - Source On - State Resistance vs. Drain Current(IV)

1000 $V_{GS} = 4.0V$ $T_a = 125^{\circ}C$ $T_a = 75^{\circ}C$ $T_a = 25^{\circ}C$ $T_a = -25^{\circ}C$ $T_a = -25^{\circ}C$

120 100 Drain Current Dissipation : I_D/I_D max. (%) 80 60 40 20 0 25 50 75 100 125 150 175 0 Junction Temperature : T_i [°C]

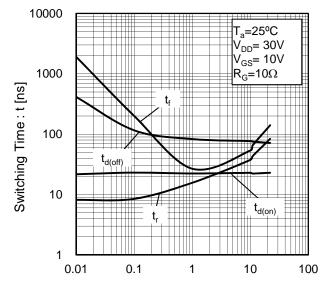
Fig.18 Drain Current Derating Curve

Fig.19 Typical Capacitance vs. Drain - Source Voltage



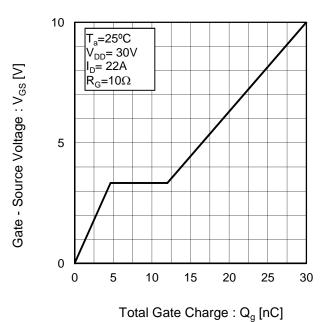
Drain - Source Voltage : V_{DS} [V]

Fig.20 Switching Characteristics



Drain Current : I_D [A]

Fig.21 Dynamic Input Characteristics



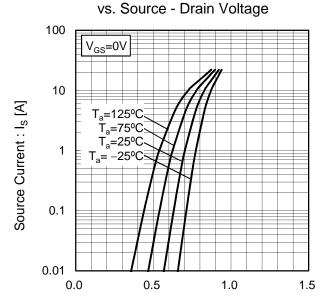
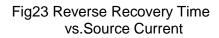
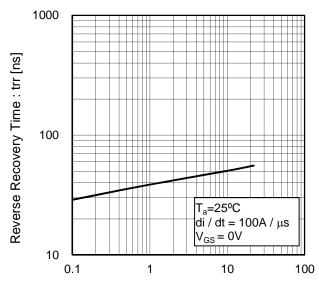


Fig.22 Source Current

Source-Drain Voltage : V_{SD} [V]





Source Current : I_S [A]

●Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

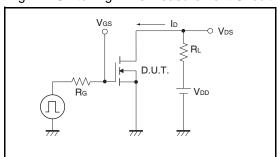


Fig.2-1 Gate Charge Measurement Circuit

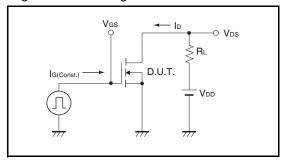


Fig.3-1 Avalanche Measurement Circuit

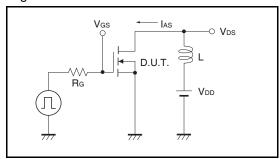


Fig.1-2 Switching Waveforms

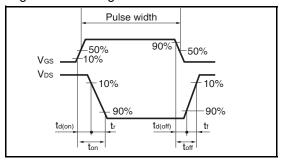


Fig.2-2 Gate Charge Waveform

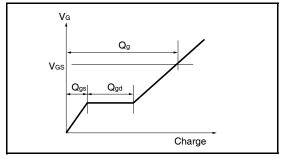
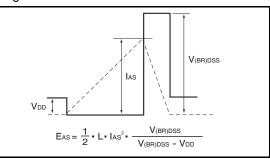
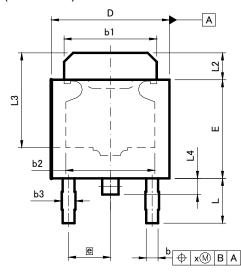


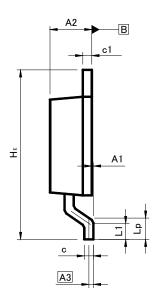
Fig.3-2 Avalanche Waveform

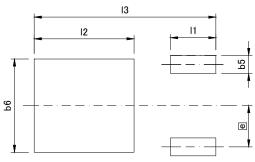


●Dimensions (Unit : mm)









DIM	MILIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
A1	0.00	0.15	0	0.006
A2	2.20	2.50	0.087	0.098
A3	0.	25	0.	01
b	0.55	0.75	0.022	0.03
b1	5.00	5.30	0.197	0.209
b2	5.	00	0.	20
b3	0.	75	0.	03
С	0.40	0.60	0.016	0.024
c1	0.40	0.60	0.016	0.024
D	6.30	6.70	0.248	0.264
Е	5.40	5.80	0.213	0.228
е	2.	30	0.	09
HE	9.00	10.00	0.354	0.394
L	2.20	2.80	0.087	0.11
L1	0.80	1.40	0.031	0.055
L2	1.20	1.80	0.047	0.071
L3	5.	30	0.2	.09
L4	0.	90	0.0	35
Lp	1.00	1.60	0.039	0.063
х	_	0.25	_	0.01

DIM MILIME		ETERS	INCHES		
DIM	DIM MIN		MIN	MAX	
b5	_	1.00	_	0.04	
b6	-	5.20	-	0.205	
11	-	2.50	-	0.098	
12	-	5.50	-	0.217	
13	-	10.00	-	0.394	

Dimension in mm/inches

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JAPAN	USA	EU	CHINA
CLASSⅢ	CLASSⅢ	CLASS II b	CL ACCIII
CLASSIV	CLASSIII	CLASSⅢ	CLASSIII

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 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
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- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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 - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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